

華泰電子股份有限公司

Orient Semiconductor Electronics, Ltd.

(股票代號:2329)

2025年法人說明會 INVESTOR CONFERENCE

14 NOV,2025



Summary

- Part 1 Company Profile
- Part 2 Manufacture Service & Product
- Part 3 2024 Q3 Financial Performance
- Part 4 Competitive Advantage
- Part 5 Q&A





Company Profile





Company History



資本額 Capital: US\$ 216M(NTD6.59B)

Common Stock : US\$ 184M Preferred C Stock : US\$ 32M

2025

54th Anniversary Celebration

2015 & 2020

Strategic Partnership Announcement

2014

1st 16D microSD in the world

2005

Biz Transformation into Memory Market

Apr, 1994

IPO in Taiwan Stock Exchange (TSE: 2329)

1971 Established

Founder: Dr. Eugene C. Y. Duh

Headquarters: Kaohsiung, Taiwan



Factory



Headquarters (Flash Memory) (750,000 sq. ft.)

- >> 6 Production buildings in NTIP
- >> Headcount: around 5,800



Facility 2 (59,223 sq. ft.)



LIC (256,200 sq. ft.)



Facility 1 (146,475 sq ft.)



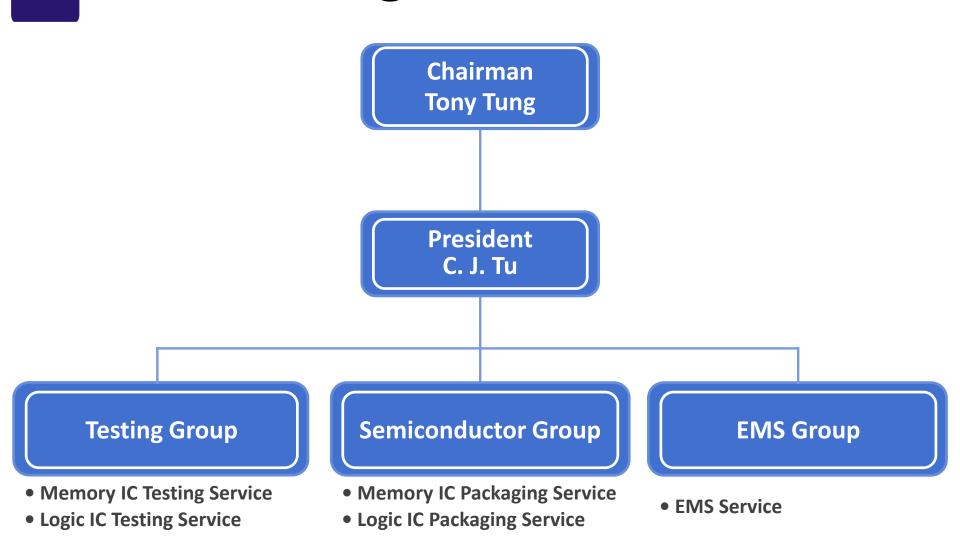
Facility 3 (158,638 sq. ft.)



Facility 5 (190,000 sq. ft.)



Organization





Manufacture Service & Product





Total Solution



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Total Solution

>>> Electronics Manufacturing Service



Product Design from Customer



JDM, DFM, DFT



NPI & Quick Turn Prototyping



Material Procurement





Repair and Upgrade



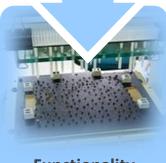
Distribution Support



System Integration



Box Build



Functionality & Reliability Testing



Product Application



Memory

Consumer Electronics

Industrial

Automotive

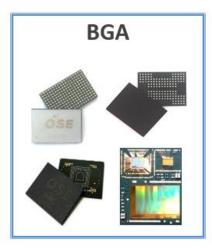
Aerospace

Communication











^{*}Includes Wire Bond Type, Flip Chip Type, SiP, etc



2025 Q3 **Financial Performance**





CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (QoQ)

| (Thousands of NTD) | Q3/2025 | % | Q2/2024 | % | Variance |
|---------------------------|-----------|---------|-----------|---------|----------|
| Net revenue | 5,187,966 | 100.00% | 5,263,888 | 100.00% | (1.44%) |
| Gross profit | 846,337 | 16.31% | 787,827 | 14.97% | 7.43% |
| Operating income | 472,954 | 9.12% | 419,883 | 7.98% | 12.64% |
| Income before tax | 538,656 | 10.38% | 409,022 | 7.77% | 31.68% |
| Income tax(expense) gains | (106,634) | (2.06%) | (21,829) | (0.41%) | 388.50% |
| Non controlling interests | - | - | - | - | - |
| Net Income | 432,022 | 8.33% | 387,193 | 7.36% | 11.58% |
| Basic EPS (in NTD) | 0.6 | - | 0.54 | - | - |
| EBITDA | 806,640 | 15.55% | 669,705 | 12.72% | 20.45% |

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CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME (YoY)

| (Thousands of NTD) | Q3/2025 | % | Q3/2024 | % | Variance |
|----------------------------|-----------|---------|-----------|---------|----------|
| Net revenue | 5,187,966 | 100.00% | 3,914,051 | 100.00% | 32.55% |
| Gross profit | 846,337 | 16.31% | 500,548 | 12.79% | 69.08% |
| Operating income (loss) | 472,954 | 9.12% | 186,906 | 4.78% | 153.04% |
| Income (loss) before tax | 538,656 | 10.38% | 219,730 | 5.61% | 145.14% |
| Income tax (expense) gains | (106,634) | (2.06%) | (42,439) | (1.08%) | 151.26% |
| Non controlling interests | - | - | - | - | - |
| Net Income | 432,022 | 8.33% | 177,291 | 4.53% | 143.68% |
| Basic EPS (in NTD) | 0.6 | - | 0.25 | - | 140.00% |
| EBITDA | 806,640 | 15.55% | 449,209 | 11.48% | 79.57% |

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主動創新 INNOVATION 積極用心 PROACTIVENESS



Key Items & Index of Balance Sheet

| (Thousands of NTD) | Q3/2025 | Q2/2025 | Variance |
|--|------------|------------|----------|
| Cash and cash equivalents | 2,598,355 | 3,437,751 | (24.42%) |
| Financial assets measured at amortized cost | - | - | - |
| Financial assets-Noncurrent & Investments-equity method | 1,882,938 | 1,441,800 | 30.60% |
| Property, plant, and equipment | 7,477,877 | 6,982,388 | 7.10% |
| Total assets | 20,139,624 | 20,317,276 | (0.87%) |
| | | | |
| Short-term loans & Short-term notes payable | - | - | - |
| Long-Term Liabilities-Current Portion | 487,885 | 465,872 | 4.73% |
| Long-term loans | 1,054,882 | 897,925 | 17.48% |
| Total liabilities | 8,480,018 | 9,163,846 | (7.46%) |
| Total stockholders' equity | 11,659,606 | 11,153,430 | 4.54% |
| Quarterly EBITDA | 806,640 | 669,705 | 20.45% |
| Index | | | |
| Debt ratio | 42.11% | 45.10% | |
| Accounts receivable turnover days(Q3) | 90 Days | 78 Days | |
| Inventory turnover days(Q3) | 40 Days | 37 Days | |

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Key Items & Index of Balance Sheet

| (Thousands of NTD) | Q3/2025 | Q3/2024 | Variance |
|--|------------|------------|--------------|
| Cash and cash equivalents | 2,598,355 | 4,392,800 | (40.85%) |
| Financial assets measured at amortized cost | - | - | - |
| Financial assets-Noncurrent & Investments-equity method | 1,882,938 | 1,799,522 | 4.64% |
| Property, plant, and equipment | 7,477,877 | 6,129,265 | 22.00% |
| Total assets | 20,139,624 | 19,231,283 | 4.72% |
| Short-term loans & Short-term notes payable | - | _ | - |
| Long-Term Liabilities-Current Portion | 487,885 | 325,248 | 50.00% |
| Long-term loans | 1,054,882 | 984,067 | 7.20% |
| Total liabilities | 8,480,018 | 7,889,705 | 7.48% |
| Total stockholders' equity | 11,659,606 | 11,341,578 | 2.80% |
| Overterly EDITDA | - | - | 0/ |
| Quarterly EBITDA | 806,640 | 449,209 | 79.57% |
| Index | | | |
| Debt ratio | 42.11% | 41.03% | |
| Accounts receivable turnover days(Q1~Q3) | 88 Days | 95 Days | |
| Inventory turnover days(Q1~Q3) | 39 Days | 45 Days | |

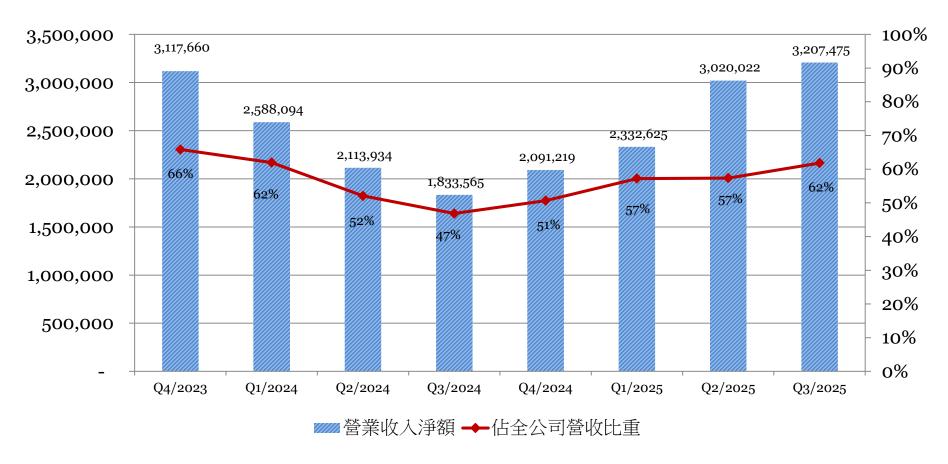
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IC Packaging and Testing Services

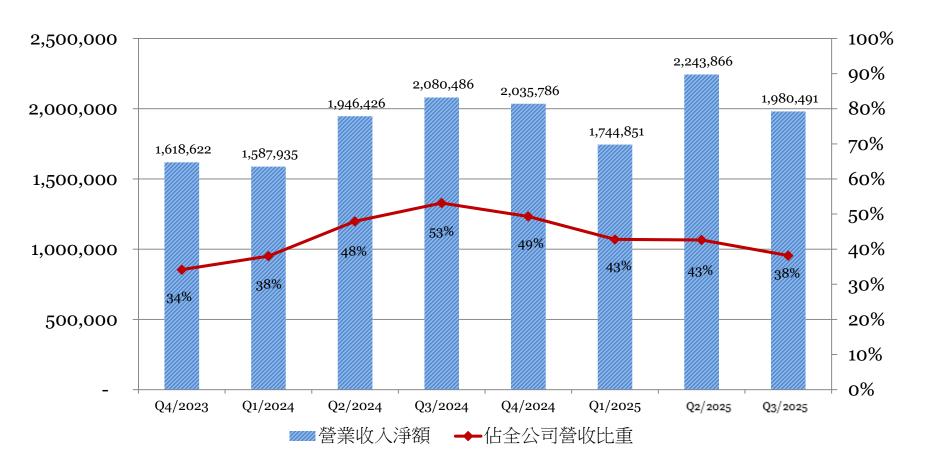
(Thousands of NTD)





Electronics Manufacturing Services

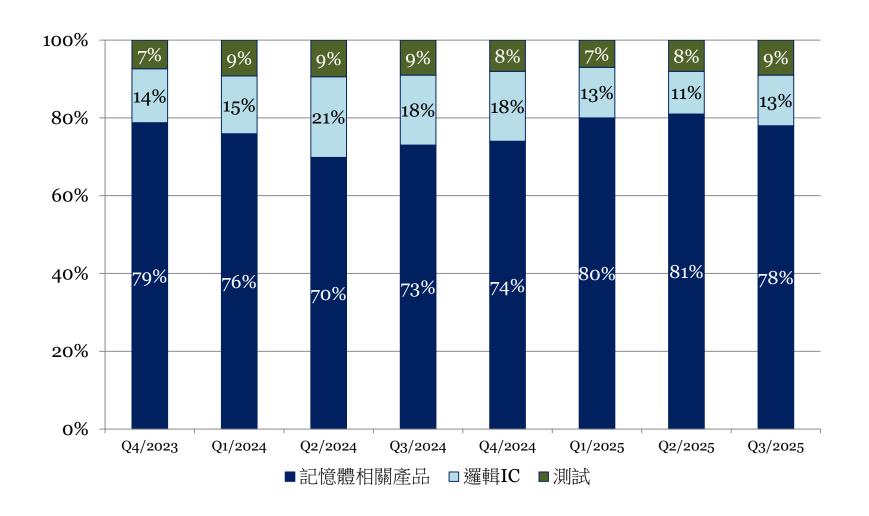
(Thousands of NTD)





Semiconductor Group

-Percentage of revenue by product application





2025 Q3 Operation Status Summary

Semiconductor BU

- The memory industry has become a Seller's market.
- Memory customers are actively stocking up, driving semiconductor revenue recovery and increasing its proportion of total company revenue.
- IC capacity utilization remains high.

EMS BU

- Strong demand from AI server customers.
- Memory customers are actively stocking up; vertically integrated production of memory modules.



Competitive Advantage



INNOVATION





- Focus on Memory Market for 20 years.
- Efficient Manufacture Platform for Memory.



- Advanced Process Capability
 - 25um wafer thickness
 - 16 Layers Die Stacking for microSD/BGA/SD
 - 1ST 1TB microSD announced to market



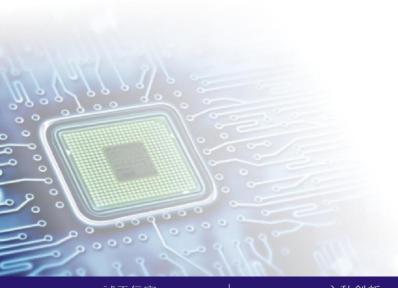
- Highly Systematized Production Environment
- MES Automation System



- One-Stop Service
- High Degree of Flexibility on capacity allocation



Q&A



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Disclaimer

The presentation and the relevant information mentioned in this material have been compiled from both internal and external resources.

These forward looking statements involve known and unknown risks, uncertainties and other factors, including price variation, competition, global economy, exchange rate movement and market demand, which may cause actual results to differ materially from those implied by such forward-looking statements.

The forward looking statements expressed in this material reflect the Company's current view about the future as of today. The Company is not responsible for any updates if there are any changes in the future.